

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3282588

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ARITO OGAWA	02/19/2014
TSUYOSHI TAKEDA	02/19/2014
RECEIVING PARTY DATA	
Name:	HITACHI KOKUSAI ELECTRIC INC.
Street Address:	14-1, SOTOKANDA 4-CHOME
Internal Address:	CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	1018980
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14668714
CORRESPONDENCE DATA	
Fax Number:	(215)568-6499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	215-568-6400
Email:	ppetaccia@vklaw.com
Correspondent Name:	VOLPE AND KOENIG, P.C.
Address Line 1:	30 SOUTH 17TH STREET, 18TH FLOOR
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	HITACHI13-21010279US03
NAME OF SUBMITTER:	KEIKO KIMURA MIDDLETON
SIGNATURE:	/Keiko Kimura Middleton/
DATE SIGNED:	03/25/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 4	
source=HITACHI13_21010279US03_Assignment#page1.tif	
source=HITACHI13_21010279US03_Assignment#page2.tif	
source=HITACHI13_21010279US03_Assignment#page3.tif	

CONTINUATION APPLN.

HITACHI13-21010279US03

Atty. Docket No. ~~HITACHI13-21010279US02~~

ASSIGNMENT AND DECLARATION

With respect to the invention titled

**METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, METHOD OF
PROCESSING SUBSTRATE, SUBSTRATE PROCESSING APPARATUS AND
COMPUTER-READABLE RECORDING MEDIUM**

for which the undersigned has authorized or prepared an application for United States Letters Patent, U.S. Patent Application No. 14/668,714, filed on March 25, 2015

I (the undersigned) hereby state the following.

DECLARATION

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

ASSIGNMENT

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Assignee

HITACHI KOKUSAI ELECTRIC INC.

Atty. Docket No.

Assignee State or Country
of Incorporation

Japan

Assignee Address

14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan

Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

AND this Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

Atty. Docket No.

**SIGNATURE SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name OGAWA, Arito
Inventor's Signature Arito Ogawa
Date February 19, 2014
Signed at Toyama-shi, Japan
(City and Country)

STATEMENT OF WITNESS (optional):

I, _____
Name of Witness

was personally present and did see OGAWA, Arito
inventor identified above

execute this Assignment on _____ and such Assignor is personally known
date

to me to be the person described herein.

Witness
Signature _____

An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use a separate form for each inventor; or check the box below and complete the attached page(s) to list additional inventors.

■ Additional inventors are being named on the 1 supplemental sheet(s) attached hereto.

Atty. Docket No.

**SUPPLEMENTAL SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name TAKEDA, Tsuyoshi

Inventor's Signature 竹田 泰吉

Date Feb 19, 2014

Signed at Toyama-shi, Japan
(City and Country)

STATEMENT OF WITNESS (optional):

I, _____
Name of Witness

was personally present and did see TAKEDA, Tsuyoshi
inventor identified above

execute this Assignment on _____ and such Assignor is personally known
date

to me to be the person described herein.

Witness
Signature _____